



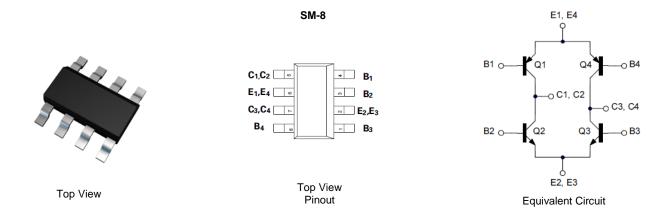
20V BIPOLAR TRANSISTOR H-BRIDGE IN SM-8

Features

- BJT H-Bridge
- 2 x NPN + 2 x PNP
- I_C = 2.5A Continuous Collector Current
- NPN Transistor
 - BV_{CEO} > 20V
 - Low Saturation Voltage V_{CE(sat)} < 150mV @ 1A
- PNP Transistor
 - BV_{CEO} > -20V
 - Low Saturation Voltage V_{CE(sat)} < -200mV @ -1A
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SM-8 (8 LEAD SOT223)
- Case Material: Molded Plastic, "Green" Molding Compound;
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads.
 Solderable per MIL-STD-202, Method 208
- Weight: 0.117 grams (Approximate)



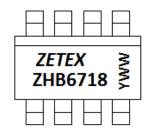
Ordering Information (Note 4)

Part Number	Marking	Reel Size (inches)	Tape Width (mm)	Quantity Per Reel
ZHB6718TA	ZHB6718	7	12	1,000

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen and Antimony free, "Green" and Lead-Free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



ZHB6718 = Product Type Marking Code YWW = Date Code Marking Y or \overline{Y} = Last Digit of Year (ex: 5= 2015) WW or $\overline{W}W$ = Week Code (01~53)



Absolute Maximum Ratings (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	NPN	PNP	Unit
Collector-Base Voltage	V _{CBO}	20	-20	V
Collector-Emitter Voltage	V _{CEO}	20	-20	V
Emitter-Base Voltage	V _{EBO}	7	-7	V
Continuous Collector Current	Ic	2.5	-2.5	Α
Peak Pulse Current (Note 5)	Ісм	6	-6	Α

Thermal Characteristics

Characteristic	Symbol	Value	Unit		
Callacter Dower Dissinction	(Note 5)	2	1.25	W	
Collector Power Dissipation	(Note 6)	P _D	2	VV	
The second Decistors of Lunction to Ambient	(Note 5)	5	100	0000	
ermal Resistance, Junction to Ambient	(Note 6)	$R_{\theta JA}$	62.5	°C/W	
Thermal Resistance, Junction to Lead		$R_{ heta JL}$	62	°C/W	
Operating and Storage Temperature Range		$T_{J_i}T_{STG}$	-55 to +150	°C	

ESD Ratings (Note 7)

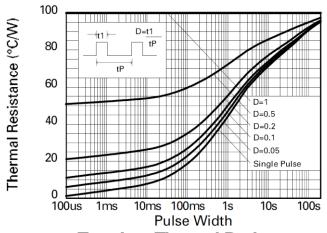
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	С

Notes:

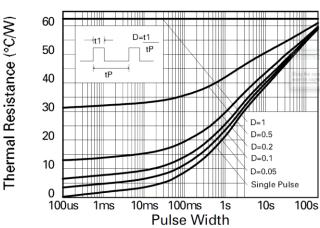
- 5. For a device with any single die active and mounted with the collector lead on 25mm x 25mm 2oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in steady-state.
- 6. Same as Note (5), except both Q1/Q3 active or Q2/Q4 active and equally sharing power.
- 7. Refer to JEDEC specification JESD22-A114 and JESD22-A115.



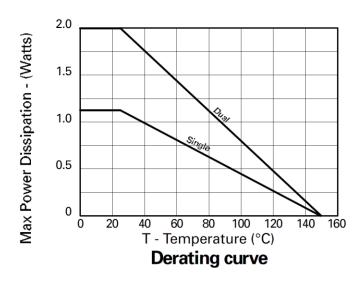
Thermal Characteristics and Derating Information

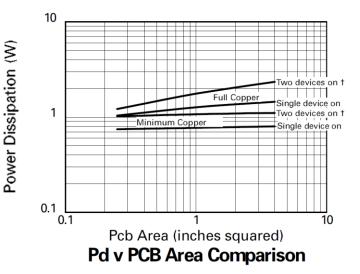


Transient Thermal Resistance Single Transistor "On"



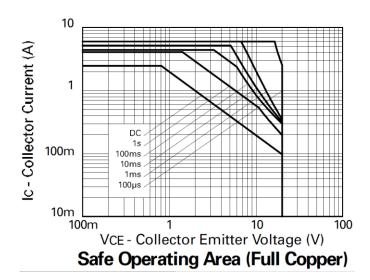
Transient Thermal Resistance Q1 and Q3 or Q2 and Q4 "On"

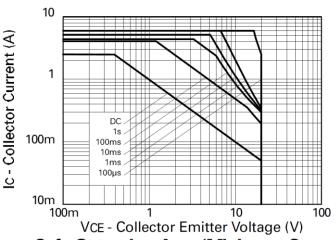






Thermal Characteristics and Derating Information (continued)





Safe Operating Area (Minimum Copper)

Note:

The Safe Operating Area (SOA) charts shown are a combination of the worst case secondary breakdown characteristics for the NPN/PNP pair, and the thermal curves demonstrating the power dissipation capability of the energized ZHB part (opposing NPN-PNP switched on) when mounted on a 50mm \times 50mm FR4 PCB. The two cases show:

i) full copper present and

ii) with minimal copper present — this being defined as an SM-8 footprint with 1.5mm tracks to the edge of the PCB.

For example, on a 50mm x 50mm full copper PCB, the ZHB6718 will safely dissipate 2W under DC conditions, taking note of continuous current ratings and voltage limits. Higher powers can be tolerated for pulsed operation, while the shorter pulse widths (100µs and 1ms) being relevant for assessment of switching conditions.



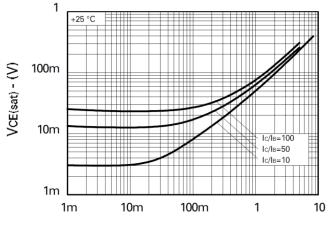
NPN - Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV _{CBO}	20	100	_	V	I _C = 100μA
Collector-Emitter Breakdown Voltage (Note 8)	BV _{CEO}	20	27	_	V	I _C = 10mA
Emitter-Base Breakdown Voltage	BV _{EBO}	5	8.3	_	V	I _E = 100μA
Collector Cut Off Current	I _{CBO}	_	_	0.1	μΑ	V _{CB} = 16V
Emitter Cut Off Current	I _{EBO}	_	_	0.1	μΑ	V _{EB} = 4V
		200	400	_		I _C = 10mA, V _{CE} = 2V
DC Current Transfer Static Patic (Note 9)	h _{FE}	300	450	_	_	I _C = 100mA, V _{CE} = 2V
DC Current Transfer Static Ratio (Note 8)		200	360	_		$I_C = 2A, V_{CE} = 2V$
		_	180	_		$I_C = 6A, V_{CE} = 2V$
	V _{CE(sat)}	_	8	15	mV	$I_C = 0.1A, I_B = 10mA$
Collector-Emitter Saturation Voltage (Note 8)		_	70	150		$I_C = 1A, I_B = 10mA$
		_	130	200		I _C = 2.5A, I _B = 50mA
Base-Emitter Saturation Voltage (Note 8)	V _{BE(sat)}	_	0.89	1.0	V	I _C = 2.5A, I _B = 50mA
Base-Emitter Turn-on Voltage (Note 8)	V _{BE(on)}	_	0.79	_	V	I _C = 2.5A, V _{CE} = 2V
Transitional Frequency	f⊤	100	140	_	MHz	I _C = 50mA, V _{CE} = 10V, f = 100MHz
Output Capacitance	C _{obo}	_	23	30	pF	V _{CB} = 10V, f = 1MHz
Suitabing Time	t _(ON)	_	170	_	nS	V _{CC} = 10V, I _C = 1A,
Switching Time	t _(Off)	_	400	_	nS	$I_{B1} = -I_{B2} = 10$ mA

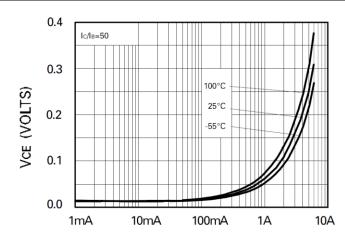
Note: 8. Measured under pulsed conditions. Pulse width \leq 300 μ s. Duty cycle \leq 2%.



NPN - Typical Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)



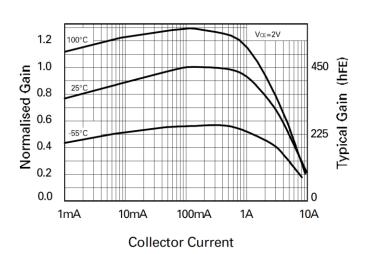
IC - Collector Current (A)



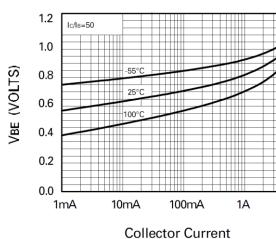
Collector Current

VCE(sat) vs IC

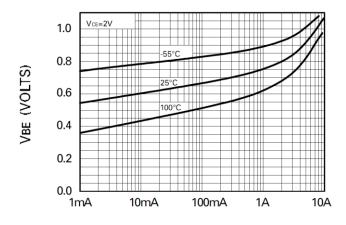
VCE(sat) v IC



hfe vs IC



VBE(sat) vs IC



VBE(on) vs IC

Collector Current

10A



PNP - Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

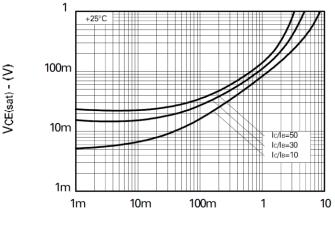
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV _{CBO}	-20	-65	_	V	I _C = -100μA
Collector-Emitter Breakdown Voltage (Note 9)	BV _{CEO}	-20	-55	_	V	I _C = -10mA
Emitter-Base Breakdown Voltage	BV _{EBO}	-5	-8.8	_	V	$I_E = -100 \mu A$
Collector Cutoff Current	I _{CBO}	_	_	-0.1	μA	V _{CB} = -15V
Emitter Cutoff Current	I _{EBO}	_	_	-0.1	μΑ	V _{EB} = -4V
		300	475	_		I _C = -10mA, V _{CE} = -2V
		300	450	_	_	$I_C = -100 \text{mA}, V_{CE} = -2 \text{V}$
DC Current Transfer Static Ratio (Note 9)	h _{FE}	150	230	_		$I_C = -2A$, $V_{CE} = -2V$
		35	70	_		$I_C = -4A$, $V_{CE} = -2V$
		_	30	_		$I_C = -6A, V_{CE} = -2V$
	VCE(sat)	_	-16	-40	mV	I _C = -100mA, I _B = -10mA
Collector-Emitter Saturation Voltage (Note 9)		_	-130	-200		$I_C = -1A$, $I_B = -20mA$
		_	-190	-260		$I_C = -2.5A$, $I_B = -200mA$
Base-Emitter Saturation Voltage (Note 9)	V _{BE(sat)}	_	-0.98	-1.1	V	$I_C = -2.5A$, $I_B = -200mA$
Base-Emitter Turn-on Voltage (Note 9)	V _{BE(on)}	_	-0.85	_	V	I _C = -2.5A, V _{CE} = -2V
Transitional Frequency	f _T	150	180	_	MHz	$I_C = -50 \text{mA}, V_{CE} = -10 \text{V},$ f = 100MHz
Output Capacitance	C _{obo}	_	21	30	pF	V _{CB} = -10V, f = 1MHz
Switching Time	t _(ON)		40		nS	$V_{CC} = -10V, I_{C} = -1A,$
Switching Time	t _(OFF)	_	670	_	nS	$I_{B1} = -I_{B2} = -20\text{mA}$

Note:

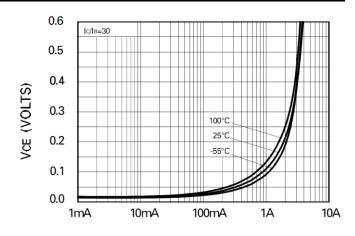
9. Measured under pulsed conditions. Pulse width \leq 300 μ s. Duty cycle \leq 2%.



PNP - Typical Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

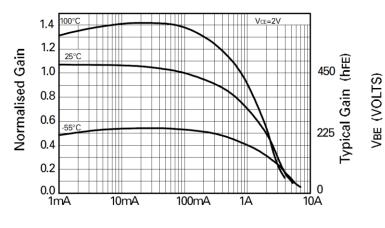






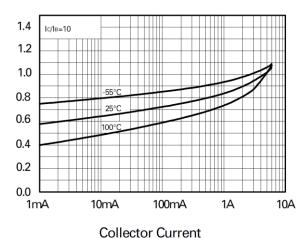
Collector Current

VCE(sat) v IC



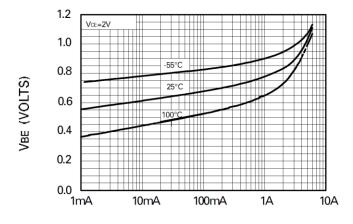
Collector Current

VCE(sat) vs IC



VBE(sat) vs IC

hFE vs IC



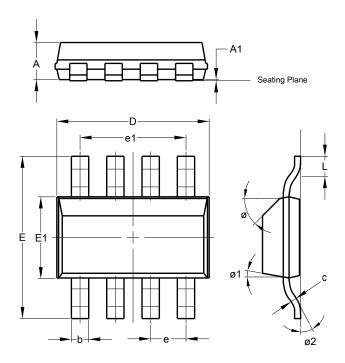
Collector Current

VBE(on) vs IC



Package Outline Dimensions

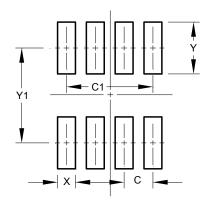
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



SM-8						
Dim	Min	Max	Тур			
Α		1.70	1.60			
A1	0.02	0.10	0.04			
b	0.70	0.90	0.80			
С	0.24	0.32	0.28			
D	6.30	6.70	6.60			
е	1.53 REF					
e1		4.59 RE	F			
Е	6.70	7.30	7.00			
E1	3.30	3.70	3.50			
L	0.75	1.00	0.90			
Ø			45°			
Ø1		15°				
Ø2	1		10°			
All Dimensions in mm						

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)				
С	1.52				
C1	4.60				
Х	0.95				
Υ	2.80				
Y1	6.80				

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device terminals and PCB tracking.



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